Barrel Strip Sensors Update

LVII. PANDA Meeting, GSI - June 2016

## $1{ }^{\text {st }}$ Production Batch

- Ordered 4 Lots with 25 wafer each end of 2014
$\rightarrow 80$ wafers to be delivered (assuming $80 \%$ yield)
- Status 2015
- 3 lots delivered in mid 2015:
- lot 341774
- lot 341775
- lot 341776
- Only sensors that passed the tests are delivered to Giessen
- So far: low yield


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- Status 2015
- 3 lots delivered in mid 2015:
- lot 341774
- lot 341775
- lot 341776
- Update 2016
- 3 lots delivered in May 2016:
- lot 342563
- lot 341772
- lot 352157
- Still low yield - but there is hope ...


## $1^{\text {st }}$ Production Batch



## 2015 Delivery

- Yield overview first 3 lots

| Lot | b65 (S1) | m65 (S2) |
| :---: | :---: | :---: |
| 341774 | $5(20 \%)$ | $10(40 \%)$ |
| 341775 | $1(4 \%)$ | $2(8 \%)$ |
| 341776 | $7(28 \%)$ | $9(36 \%)$ |
| total | $\mathbf{1 3}(\mathbf{1 7 \% )}$ | $\mathbf{2 1 ( 2 8 \% )}$ |

- Reasons for exclusion/failed test

| Reason | b65 (S1) | m65 (S2) |
| :---: | :---: | :---: |
| IV excluded | $24(32 \%)$ | $13(17 \%)$ |
| pin-hole excluded | $32(43 \%)$ | $20(27 \%)$ |
| broken/missing | $1(1 \%)$ | $4(5 \%)$ |
| "omitted" | $5(7 \%)$ | $17(23 \%)$ |

## 2016 Delivery

- 3 new lots delivered
- produced 2015 and 2016
- time needed to investigate issues
- Production year
- lot 342563-2015
- lot 341772-2016
- lot 352157-2016 (different wafer material)


## 2016 Delivery

- Yield overview new 3 lots

| Lot | b65 (S1) | m65 (S2) |
| :---: | :---: | :---: |
| 342563 | $8(32 \%)$ | $4(16 \%)$ |
| 341772 | $3(12 \%)$ | $2(8 \%)$ |
| 352157 | $17(68 \%)$ | $16(64 \%)$ |
| total | $\mathbf{2 8 ( 3 7 \% )}$ | $\mathbf{2 2 ( 2 9 \% )}$ |

- Reasons for exclusion/failed test

| Reason | b65 (S1) | m65 (S2) |
| :---: | :---: | :---: |
| IV excluded | $3(4 \%)$ | $12(16 \%)$ |
| pin-hole excluded | $31(41 \%)$ | $8(11 \%)$ |
| broken/missing | $5(7 \%)$ | $6(8 \%)$ |
| "omitted" | $8(11 \%)$ | $27(36 \%)$ |

## 2016 Delivery

- Characteristics compared qualitatively to first delivery
- Lot 342563
- leakage current very low to intermediate
- breakdown voltage OK (mostly >300V)
- high pin-hole count (mostly n-side)
- Lot 341772
- leakage current low to intermediate
- small breakdown voltage (220-280V)
- vey high pin-hole count (mostly n-side)
- Lot 352157
- leakage current very low to low ( $<1 \mu \mathrm{~A} @ 100 \mathrm{~V}$ for S1)
- high breakdown voltage (sometimes not reached at 500V)
- low pin-hole count (several sensors with 0 on p - and n -side)


## Outlook (the hope)

- Problems identified: surface of wafer backside (n-side)
- Last lot (352157) looks very promising
- used different wafer material (according to CiS)
- 2 more lots already produced $(352155,352156)$
- not fully measured and diced
- Lot 352155
- leakage current very low to low
- high breakdown voltage
- low pin-hole count (several defect free sensors)
- Lot 352156
- leakage current low to intermediate
- high breakdown voltage
- only a subset of pin-hole data available until now


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Total Inventory
b65 (S1) m65 (S2)

Sum 41 46

- low pin-hole count (several defect free sensors)
- Lot 352156
- leakage current low to intermediate
- high breakdown voltage
- only a subset of pin-hole data available until now

GIESSEN

## Thank you for your Attention

## Oops!

